

What is claimed is:

1. A semiconductor package in which a leadframe pad to which a semiconductor die is attached and inner leads electrically connected to the leadframe pad are covered by a molded housing, and outer leads extending from the inner leads protrude from a side surface of the molded housing to the outside,

wherein the outer leads include a first outer lead disposed in a central portion of the molded housing, and second and third outer leads respectively disposed in right and left portions of the first outer lead,

wherein the second and third outer leads each have bent portions in portions where they are adjacent to the side surface of the molded housing, the bent portions protruding to increase a space between the first outer lead and the bent portions in the molded housing,

wherein at least one of the bent portions of the second and third outer leads is covered by an extended portion of the molded housing.

2. The semiconductor package of claim 1, wherein a portion where the first outer lead is adjacent to the side surface of the molded housing is covered by the extended portion of the molded housing.

3. The semiconductor package of claim 2, wherein a distance between a surface of the molded housing covering the portion of the first outer lead and a surface of the molded housing covering at least one of the bent portions of the second and third outer leads is 1 mm or more.

4. The semiconductor package of claim 1, wherein a depression which is depressed toward a body of the molded housing is formed on at least one of a surface of the molded housing between the first outer lead and the second outer lead and a surface of the molded housing between the first outer lead and the third outer lead.

5. A semiconductor package in which a leadframe pad to which a semiconductor die is attached and inner leads electrically connected to the leadframe pad are covered by a molded housing, and outer leads extended from the inner leads protrude from a side surface of the molded housing to the outside,

wherein the outer leads include a first outer lead disposed in a central portion of the molded housing, second and third outer leads respectively disposed in a right and left of the first outer lead,

wherein the second and third outer leads each include inclinations in which a distance between the first outer lead and the inclinations becomes larger as a distance between the inclinations and the side surface of the molded housing becomes smaller,

wherein at least one of the inclinations of the second and third outer leads is covered by an extended portion of the molded housing.

6. The semiconductor package of claim 5, wherein a portion where the first outer lead is adjacent to the side surface of the molded housing is covered by the extended portion of the molded housing.

7. The semiconductor package of claim 6, wherein a distance between a surface of the molded housing covering the portion of the first outer lead and a surface of the molded housing covering at least one of the inclinations of the second and third outer leads is 1 mm or more.

8. The semiconductor package of claim 5, wherein a depression which is depressed toward a body of the molded housing is formed on at least one of a surface of the molded housing between the first outer lead and the second outer lead and a surface of the molded housing between the first outer lead and the third outer lead.

9. The semiconductor package of claim 5, wherein at least one of the inclinations of the second and third outer leads includes a portion which is perpendicular to a surface of the molded housing and a flat portion which is larger than a thickness of the molded housing covering the inclinations in a boundary between the inclinations and the molded housing.